



HEAT SINKS for POWER MODULES

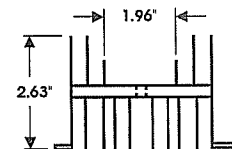
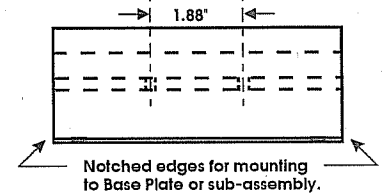
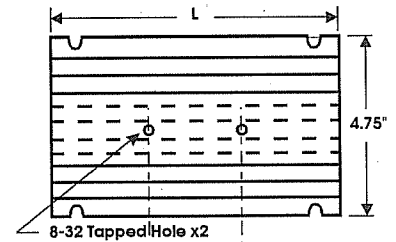
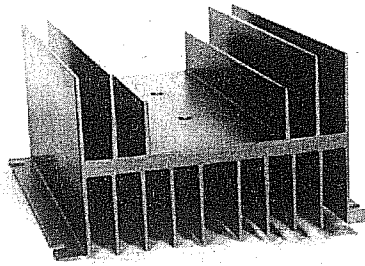
Performance Heat Sinks for Power Modules

Features:

- Extruded Fin Design
- Excellent Thermal Conductivity
- Natural and Forced Convection
- Pre-Tapped Mounting Holes

Applications:

- Power Modules
- Solid State Relays
- IGBTs
- Input/Output Modules
- Isolated Flat Base Devices
- General Purpose



The HS series are high-performance extruded fin heat sinks designed to provide maximum cooling per unit volume. The HS models have a gold chromate finish and are of an open channel design which permit mounting of standard semiconductor module styles. These models support different mounting conditions on horizontal and vertical panels for forced convection in any altitude.

For Series B, ES, M25, M50, P and T

Length	Module Ampere Rating	Part #	Price
5.5"	0-25	HS140	25.07
9.0"	25-100*	HS228	39.97

*A cooling fan with minimum rating of 100 CFM is required for module rating over 80 amps.

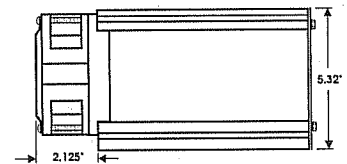
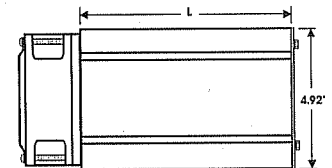
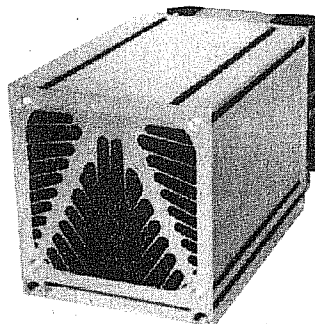
Forced Convection Assemblies for Power Modules

Features:

- Forced Convection Assemblies
- Mounting Slots Provided
- 80mm Device Mounting
- Gold Iridite Finish

Applications:

- Power Modules
- IGBTs
- Solid State Relays
- Rectifiers
- Isolated Flat Base Devices
- Multiple Component Cooling



The FCHS Series heat sinks are designed for effective cooling of single and multiple isolated power modules, IGBTs, relays and rectifiers, with standardized 80mm mounting. Integral Fan Kit includes 105 CFM 120 Vac fan, power cord, and guard. (Other configurations available. Call with your specific requirements)

For Series CD, CM, ED, IRK and SK

Length (L)	Part #	Price
4.73"	FCHS120-AC120	79.00
7.09"	FCHS180-AC120	99.00
11.82"	FCHS300-AC120	139.00

